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Investor Meeting 2022

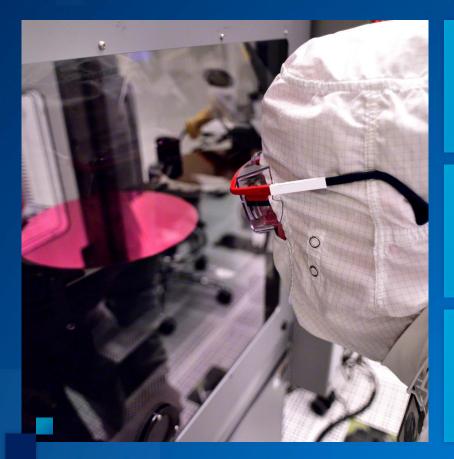
Manufacturing

Keyvan Esfarjani

Executive Vice President and Chief Global Operations Officer

intel.

Key Messages



Investing to win with IDM 2.0

Delivering Manufacturing scale for accelerating node cadence, Adv. Packaging, and Global Supply Chain resiliency

Deploying Smart Capital

Milestone based investment, Capacity optionality through shells, and Capital incentives/partners

Transforming our operating model through IFS Reducing asset downtime, Improving capital reuse, and Minimizing revenue impact

Intel's Global Manufacturing and Operations



*The Dalian fab was sold after fiscal 2021 year-end as part of the first closing of the divestiture of our NAND memory business

Intel IDM Scale Advantage

Agility

Predictability

Adaptability

> 54%

Demand mix changes supported post start of silicon by leveraging global network > 95%

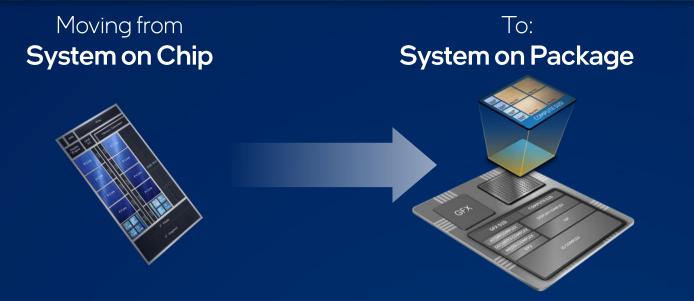
Performance vs. committed Customer Delivery Dates +\$2.2B

'21 Revenue via augmenting substrate assembly internally

Our Manufacturing Strategy



Modular Manufacturing Advantages

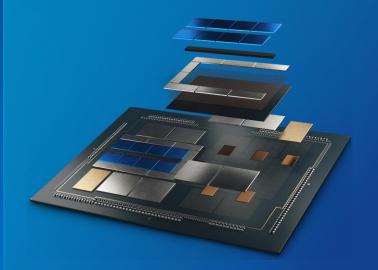


Flexibility of packaging external and internal IP's to deliver Leadership Products

Re-use of product design / tiles between products

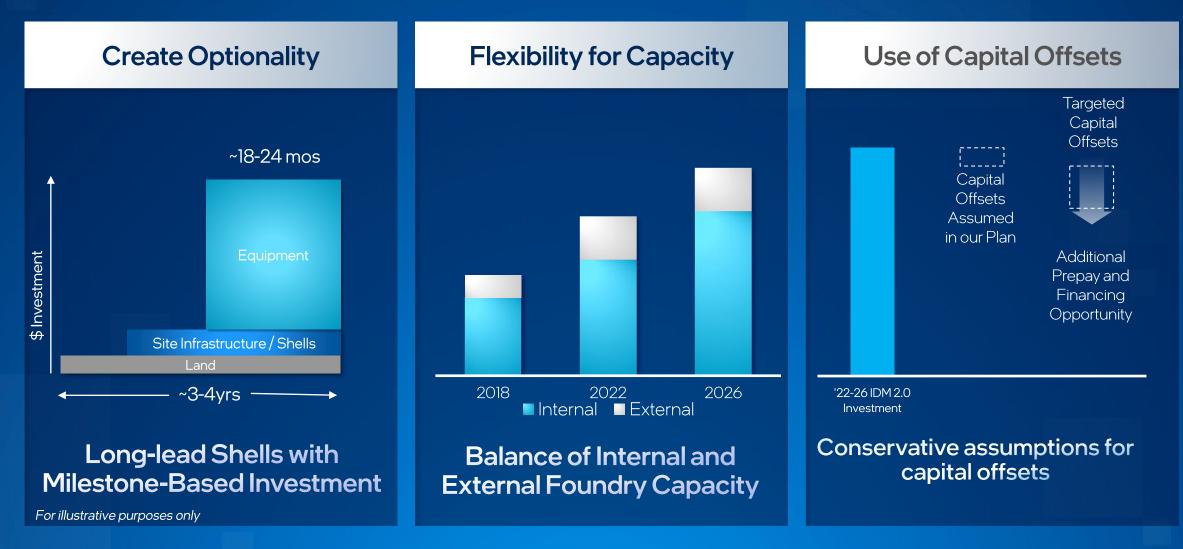
Equivalent or Better Cost Structure vs. Monolithic

Modular Manufacturing at work: **Ponte Vecchio**

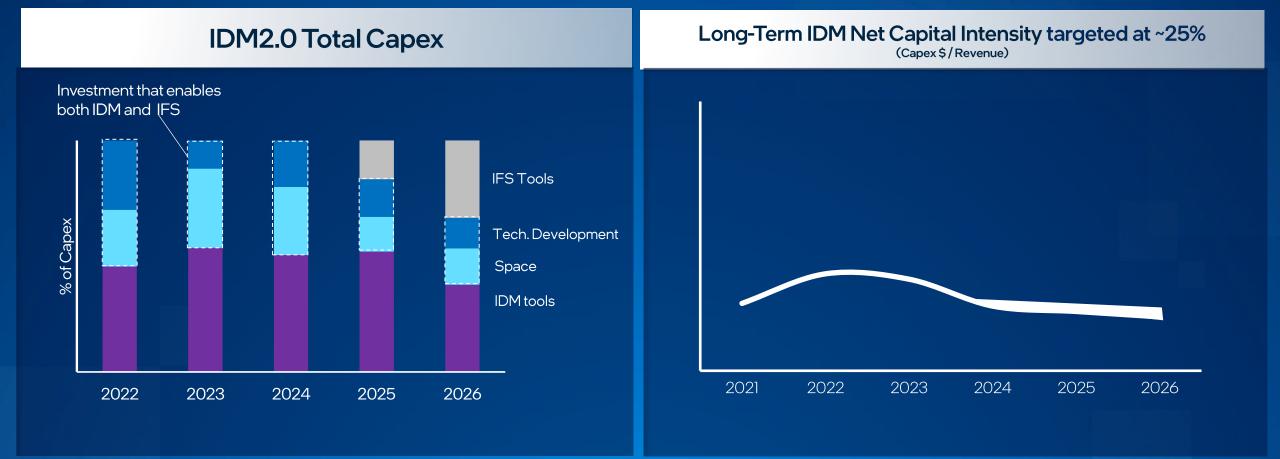


47 tiles , 5 Process Nodes 100B Transistors

Smart Capital: Optionality and Flexibility

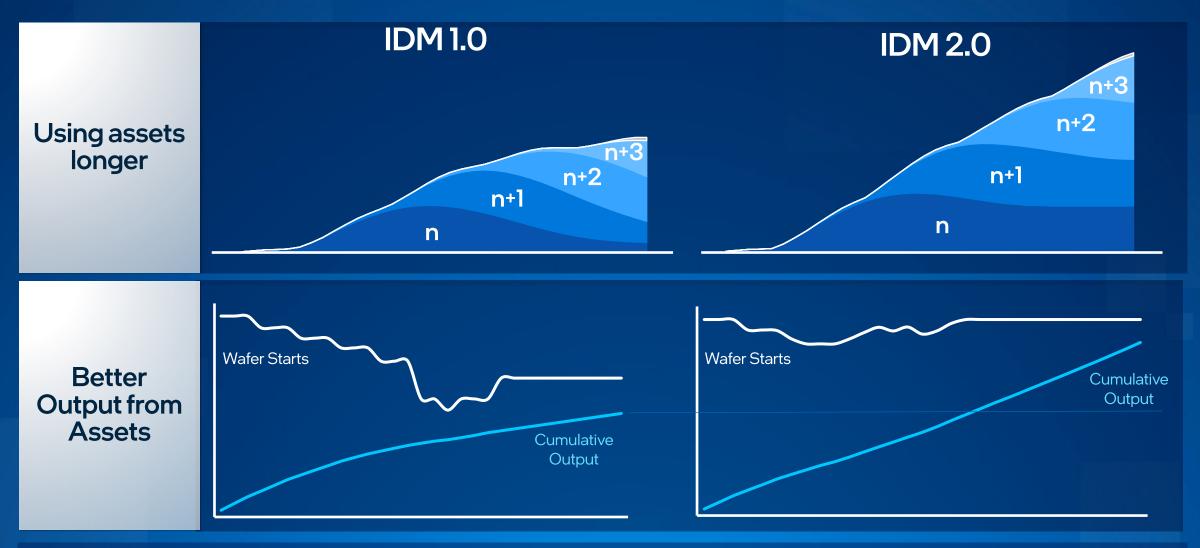


Capital Deployment



Increasing Near-Term Capital Intensity to Catch Up with Space, Accelerate TD, and Grow IFS

Transforming our Operational Model



IDM2.0 Factory: Lower Factory De-Rate, Higher Re-use, and Increased Revenue

Summary



Investing to win with IDM 2.0

Deploying Smart Capital

Transforming our operating model through IFS

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